

# Analytical Modeling of a Nanogap-Embedded FET for Application as a Biosensor

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**Abstract**—An analytical model of a nanogap-embedded field-effect transistor, which is termed here simply as a biotransistor, is developed in this study. A surface potential model is attained by solving a 2-D Poisson equation with approximation of a parabolic potential profile along the channel depth. The analytical threshold voltage is then derived from the surface potential model to comprise the unique feature of the biotransistor, which acts as a biosensor. A shift of the threshold voltage was used as a metric to ascertain the sensitivity after the biomolecule interacts with the biotransistor. Various device parameters were investigated in the developed analytical model. The characteristic trend is supported and verified via a simulation. Hence, the proposed model can provide a useful guideline for the optimal design and fabrication of a biotransistor.

**Index Terms**—Biotransistor, Dielectric-modulated field-effect transistor (DMFET), field-effect transistor (FET)-type biosensor, nanogap, nanogap-embedded FET, sensitivity, surface potential, threshold voltage, 2-D modeling, 2-D Poisson equation.

## I. INTRODUCTION

INTEREST in the use of a field-effect transistor (FET) for a range of biosensors has increased recently due to the numerous advantages that are achievable with such a design. These include miniaturization; the possibility for label-free electrical detection; high sensitivity; compatibility with traditional CMOS fabrication processes; the potential for mass-production; and feasibility for monolithic integration that combines a sensor, transducer, readout circuitry, and signal processor [1]–[16]. A large number of FET-type biosensors have been investigated in research related to nanowire FETs [1]–[5], ion-selective FETs [6]–[9], carbon nanotube FETs [10]–[12], extended-gate FETs [13], [14], and many other types. Embedding a nanogap in a traditional metal–oxide–semiconductor FET (MOSFET) structure was recently realized as a new type of biosensor based on FET technology [15]–[20]. This nanogap-embedded FET structure detects targeted biomolecules that are confined in the nanogap according to changes in electrical parameters, such as the

threshold voltage [15]–[17] or the charge-pumping current [18]–[20]. The biomolecular detection method that uses the charge-pumping technique provides information pertaining to the specific binding through monitoring of the charge-pumping current. The first demonstrated nanogap-embedded FET, which is termed dielectric-modulated FET (DMFET), uses the shift of the threshold voltage as the biomolecular sensing parameter [15]. It includes a nanogap between the gate and gate oxide. The nanogap was created by carving some parts of the sacrificial layer preexisting between the gate and gate oxide. When biomolecules filled the nanogap, the threshold voltage  $V_T$  shifted due to the change of the dielectric constant  $K$  from unity, corresponding to air, to a certain number ( $K > 1$ ), corresponding to the biomolecules. Owing to this characteristic, the aforementioned FET was termed a DMFET (simply biotransistor). However, as other types of FET-type biosensors, an analytical model to describe  $\Delta V_T$  has yet to be developed. Therefore, the development of an analytical model to describe the dielectric-modulation effect as a result of mutual interaction between the biomolecules and the biotransistor is required. In this study, as a sensing parameter in the biotransistor, the shift of the threshold voltage ( $\Delta V_T$ ) before and after immobilization of the biomolecules was used.

This work focuses on the development of an analytical  $V_T$  model of the biotransistor using a 2-D modeling technique to formulate a type of design guidance. The sensing parameter of the biotransistor is  $V_T$ , which is the most typical parameter among the numerous useful device parameters of the FET. The biotransistor is composed of three subparts of the gate dielectric. In order to suppress short-channel effects and minimize mobility degradation when a high- $k$  gate dielectric is used for the entire region of the channel, a hybrid gate dielectric structure comprised a high- $k$  component at the source edge, thermal oxide at the center, and a high- $k$  component at the drain edge is deemed suitable. The proposed analytical model can also be applied to such a hybrid gate dielectric MOSFET.

## II. STRUCTURE AND OPERATIONAL PRINCIPLE OF THE BIOTRANSISTOR

A schematic of the biotransistor is displayed in Fig. 1(a). The nanogap to induce a change of  $V_T$  is implemented at the edges of the gate in a silicon-on-insulator (SOI) substrate. A cross-sectional view [A-A' direction in Fig. 1(a)] of the biotransistor modeled in this paper is shown in Fig. 1(b). The operational principle of the biotransistor built with an n-channel is illustrated in Fig. 1(c) and (d). When the sacrificial layer ( $G_{\text{bot}}$ )

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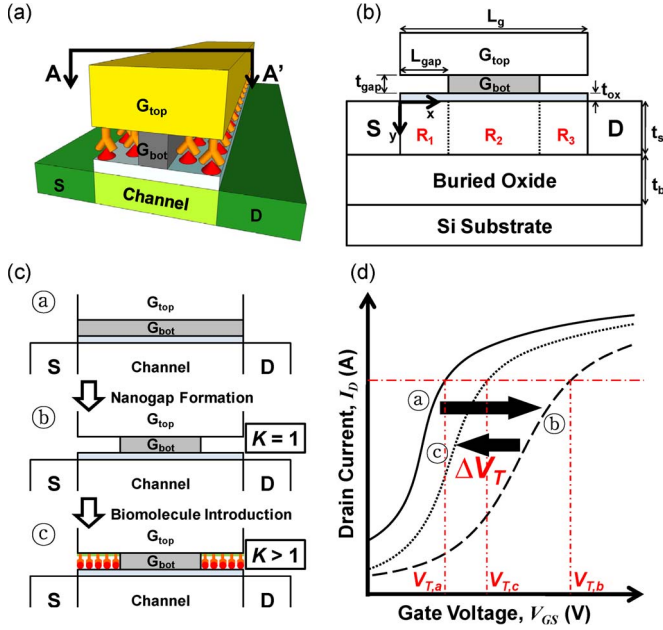


Fig. 1. Schematics of the biotransistor. (a) Three-dimensional schematic showing the biotransistor with biomolecules introduced in the nanogaps. (b) Cross-sectional view [A-A' direction in (a)] of the biotransistor. 2-D modeling is carried out in each of the three distinct regions. Regions 1 and 3 are underneath the nanogap. (c) Schematics to show the change of the dielectric constant due to nanogap formation and immobilization of the biomolecule inside the nanogap. (d) Operational principle of the biotransistor to show  $\Delta V_T$  for each step depicted in (c).

in Fig. 1(c) was etched in part, air ( $K = 1$ ) inherently filled the nanogaps. Therefore, the effective dielectric constant of the gate dielectric, which is composed of the oxide ( $K = 3.9$ ) and air, was reduced. As a result,  $V_T$  increased from  $V_{T,a}$  to  $V_{T,b}$ , as illustrated in Fig. 1(d). When biomolecules were introduced and immobilized in the nanogaps, the effective dielectric constant of the gate dielectric composed of the oxide ( $K = 3.9$ ) and the biomolecules ( $K > 1$ ) increased. As a consequence,  $V_T$  was reduced from  $V_{T,b}$  to  $V_{T,c}$ . By sensing this value of  $\Delta V_T (= V_{T,b} - V_{T,c})$ , the specific binding of biomolecules or interactions such as DNA hybridization or antigen-antibody reactions can be electrically identified without time-consuming and complicated labeling processes. This biotransistor sensing method has been experimentally demonstrated with the gate dielectric modulation effect [15]. However, as other types of FET-type biosensors, an analytical model to describe  $\Delta V_T$  has not been developed. Therefore, analytical modeling of the  $V_T$  shift in the biotransistor is necessary to optimize device parameters such as the nanogap length  $L_{\text{gap}}$ , nanogap thickness  $t_{\text{gap}}$ , gate length  $L_g$ , gate oxide thickness  $t_{\text{ox}}$ , channel thickness  $t_s$ , and the workfunctions of  $G_{\text{top}}$  and  $G_{\text{bot}}$  ( $\phi_{M,\text{top}}$ ,  $\phi_{M,\text{bot}}$ ).

### III. DERIVATION OF 2-D SURFACE POTENTIAL MODEL

Several studies have developed analytical threshold voltage models for modified structures from a traditional MOSFET [21], [22]. The procedure to attain the threshold voltage model of the biotransistor proceeds in the same manner. First, the channel potential distribution is derived by solving a 2-D Poisson equation through the use of proper assumptions and

boundary conditions. The potential profile along the channel depth is approximated to the parabolic function in SOI devices [21]–[23]. Second,  $V_T$  is derived from the potential model of the biotransistor.  $V_T$  dependence on the device parameters is comprehensively investigated. Afterward, the modeling results are verified in comparison with simulation data.

The gate of the biotransistor consists of two layers  $G_{\text{top}}$  and  $G_{\text{bot}}$ , as shown in Fig. 1(a).  $G_{\text{bot}}$  is a sacrificial layer for the formation of a lateral nanogap directly onto the gate oxide after a selective wet-etching process, whereas  $G_{\text{top}}$  acts as the main gate electrode. Details of the fabrication processes are available in the literature [15]. As the inversion charge density is assumed to be negligible in the subthreshold regime, the potential distribution  $\phi(x, y)$  in the silicon channel is expressed as

$$\frac{d^2 \phi(x, y)}{dx^2} + \frac{d^2 \phi(x, y)}{dy^2} = \frac{qN_A}{\epsilon_{\text{Si}}} \quad (1)$$

for  $0 \leq x \leq L_g$ ,  $0 \leq y \leq t_s$ , where  $q$  is the electronic charge,  $N_A$  is the doping concentration of the channel,  $\epsilon_{\text{Si}}$  is the dielectric permittivity of silicon,  $L_g$  is the gate length, and  $t_s$  is the channel thickness. It should be noted that inaccuracy  $\phi(x, y)$  can arise from the aforementioned approximation, i.e., only space charges (depletion charges) are considered. Nevertheless, this was traditionally used to obtain a closed form of  $\phi(x, y)$ . Due to the structural profile of the biotransistor, the channel region is divided into three regions  $R_j$ , as shown in Fig. 1(b), where  $j = 1, 2, 3$  denotes the left-side nanogap, essential channel, and right-side nanogap region, respectively. Given that  $R_1$  and  $R_3$  are symmetric, the effective gate capacitance  $C_{\text{eff}}$  and flat-band voltage  $V_{\text{FB}}$  in  $R_1$  and  $R_3$  are represented by

$$C_{\text{eff}} = \epsilon_{\text{ox}} \epsilon_{\text{gap}} / (\epsilon_{\text{gap}} t_{\text{ox}} + \epsilon_{\text{ox}} t_{\text{gap}})$$

$$V_{\text{FB},1} = V_{\text{FB},3} = \phi_{M,\text{top}} - \phi_{\text{Si}}$$

where  $\epsilon_{\text{ox}}$  and  $\epsilon_{\text{gap}}$  are the dielectric permittivity of the oxide and the nanogap-filling material, respectively;  $t_{\text{ox}}$  and  $t_{\text{gap}}$  are the thickness of the oxide and the nanogap-filling material (nanogap thickness), respectively;  $\phi_{M,\text{top}}$  is the workfunction of  $G_{\text{top}}$  (gold in the biotransistor, as reported in [15]); and  $\phi_{\text{Si}}$  is the workfunction of silicon. The latter value is known to be

$$\phi_{\text{Si}} = \chi_{\text{Si}} + E_g / 2q + \phi_F$$

where  $\chi_{\text{Si}}$  is the electron affinity,  $E_g$  is the silicon energy band gap, and  $\phi_F$  is the difference between the extrinsic and intrinsic Fermi potential level, i.e.,  $\phi_F = kT/q \ln(N_A/n_i)$ . The gate capacitance  $C_{\text{ox}}$  and flat-band voltage  $V_{\text{FB}}$  in  $R_2$  are correspondingly written as

$$C_{\text{ox}} = \epsilon_{\text{ox}} / t_{\text{ox}} \quad \text{and} \quad V_{\text{FB},2} = \phi_{M,\text{bot}} - \phi_{\text{Si}}$$

where  $\phi_{M,\text{bot}}$  is the workfunction of  $G_{\text{bot}}$  (chromium in the biotransistor, as presented in [15]).

A parabolic assumption along the channel depth has been commonly used as a modeling technique for fully depleted SOI devices after Young proved its validity for the first time [23].

The parabolic approximated potential distribution  $\phi(x, y)$  for each region is given by

$$\phi_j(x, y) = \phi_{S,j}(x) + c_{a,j}(x)y + c_{b,j}(x)y^2 \quad (2)$$

where  $j$  denotes each region,  $\phi_{S,j}$  is the potential at the channel surface, i.e.,  $\phi_j(x, 0)$ , and  $c_{a,j}$  and  $c_{b,j}$  are arbitrary coefficients determined as a function of  $x$  only. The coefficients  $c_{a,j}$  and  $c_{b,j}$  are calculated from the boundary conditions that satisfy the continuity of the electric displacement at the interface of the oxide and silicon channel. These are

$$\begin{cases} \left. \frac{d\phi_j(x, y)}{dy} \right|_{y=0} = \frac{C_j}{\varepsilon_{Si}} (\phi_{S,j}(x) - V_{GS} + V_{FB,j}) \\ \left. \frac{d\phi_j(x, y)}{dy} \right|_{y=t_s} = -\frac{C_B}{\varepsilon_{Si}} (\phi_B(x) - V_{SUB} + V_{FB,b}) \end{cases} \quad (3)$$

where  $V_{GS}$  is the gate-to-source bias,  $V_{SUB}$  is the substrate bias,  $V_{FB,b}$  is the flat-band voltage at the back-channel,  $\phi_B = \phi(x, t_s)$  is the potential at the back-channel surface,  $C_B = \varepsilon_{ox}/t_b$  is the back-channel oxide capacitance,  $C_1 = C_3 = C_{eff}$ , and  $C_2 = C_{ox}$ . Plugging  $\phi(x, y)$  into a 2-D Poisson equation (1), the equation is rewritten in the form of a 1-D second-order differential equation, i.e.,

$$\frac{d^2\phi_{S,j}(x)}{dx^2} - \alpha_j\phi_{S,j}(x) = \beta_j \quad (4)$$

where

$$\begin{aligned} \alpha_1 = \alpha_3 &= \frac{2(1 + C_{eff}/C_S + C_{eff}/C_B)}{t_s^2(1 + 2C_S/C_B)} \\ \beta_1 = \beta_3 &= \frac{qN_A}{\varepsilon_{Si}} - 2(V_{GS} - V_{FB,1}) \left( \frac{C_{eff}/C_S + C_{eff}/C_B}{t_s^2(1 + 2C_S/C_B)} \right) \\ &\quad - 2(V_{SUB} - V_{FB,b}) \left( \frac{1}{t_s^2(1 + 2C_S/C_B)} \right) \\ \alpha_2 &= \frac{2(1 + C_{ox}/C_S + C_{ox}/C_B)}{t_s^2(1 + 2C_S/C_B)} \\ \beta_2 &= \frac{qN_A}{\varepsilon_{Si}} - 2(V_{GS} - V_{FB,2}) \left( \frac{C_{ox}/C_S + C_{ox}/C_B}{t_s^2(1 + 2C_S/C_B)} \right) \\ &\quad - 2(V_{SUB} - V_{FB,b}) \left( \frac{1}{t_s^2(1 + 2C_S/C_B)} \right) \end{aligned}$$

and where the channel capacitance is written as  $C_S = \varepsilon_{Si}/t_s$ . If  $L_{gap}$  tends to be zero, regions  $R_1$  and  $R_3$  disappear, i.e., there are no nanogaps. Thus, the preceding equations are reduced to a simple form, which is identical to the model reported in [23]. The general solution of (4) for each region is represented as

$$\phi_{S,j}(x) = A_j \exp(\lambda_j x) + B_j \exp(-\lambda_j x) + \sigma_j \quad (5)$$

where  $\lambda_1 = \lambda_3 = \sqrt{\alpha_1}$ ,  $\sigma_1 = \sigma_3 = -\beta_1/\alpha_1$ ,  $\lambda_2 = \sqrt{\alpha_2}$ , and  $\sigma_2 = -\beta_2/\alpha_2$ . The coefficients  $A_j$  and  $B_j$  are derived from the boundary conditions satisfying continuity of the potential and electric field between adjacent regions. The built-in potential at

the source/drain edge and  $V_{DS}$  (drain-to-source bias) are also considered. These boundary conditions are represented as

$$\begin{cases} \phi_{S,1}(L_1) = \phi_{S,2}(L_1) \\ \phi_{S,2}(L_1 + L_2) = \phi_{S,3}(L_1 + L_2) \\ \left. \frac{d\phi_{S,1}(x)}{dx} \right|_{x=L_1} = \left. \frac{d\phi_{S,2}(x)}{dx} \right|_{x=L_1} \\ \left. \frac{d\phi_{S,2}(x)}{dx} \right|_{x=L_1+L_2} = \left. \frac{d\phi_{S,3}(x)}{dx} \right|_{x=L_1+L_2} \\ \phi_{S,1}(0) = V_{bi} \\ \phi_{S,3}(L_g) = V_{bi} + V_{DS} \end{cases} \quad (6)$$

where  $V_{bi} = (kT/q) \ln(N_A N_D/n_i^2)$  is the built-in potential across the channel-source junction, and  $N_D$  is the source/drain doping concentration. For simplicity,  $L_{gap}$  is replaced by  $L_1$ ; hence, the length of the essential channel  $L_2 = L_g - 2L_1$  is defined. The calculated coefficients  $A_j$  and  $B_j$  are summarized in the Appendix.

#### IV. DERIVATION OF THRESHOLD VOLTAGE MODEL

The minimum surface potential was used as a reference to define  $V_T$  because it serves as a criterion of the flow current, i.e., the barrier height. As there are three channel regions controlled by different physical device parameters, i.e.,  $\varepsilon_{ox}$ ,  $\varepsilon_{gap}$ ,  $t_{ox}$ ,  $t_{gap}$ ,  $\phi_{M,top}$ , and  $\phi_{M,bot}$ , the potential minimum values of each region should differ from each other. Accordingly, the  $V_T$  value of each region ( $V_{T,j}$ ,  $j = 1, 2, 3$ ) should also be different. Under a nominal n-channel MOSFET operation, the drain is positively biased, compared to the source. Hence, the potential minimum of  $R_3$  is always larger than that of  $R_1$ . Therefore, it is unnecessary to find  $V_T$  at  $R_3$  ( $V_{T,3}$ ). The potential minimum between  $R_1$  and  $R_2$  depends on the nanogap length, implying that both  $V_{T,1}$  and  $V_{T,2}$  must be solved. However,  $L_{gap}$  should be sufficiently large in order to create a highly sensitive biotransistor. In addition, supplementary capacitance components related with the two side walls of the  $G_{bot}$  layer become negligible as  $L_{gap}$  becomes larger. Therefore, the use of analytical modeling that considers each of the three regions as separate parallel-plate capacitors is an effective method. In this condition,  $V_{T,1}$  plays a crucial role in sensing the biomolecules. Thus, the potential minimum in  $R_1$  tends to be dominant in controlling the total  $V_T$  because  $V_{T,2}$  is no longer an important parameter for device analysis. In consideration of these necessary conditions to make the biotransistor highly sensitive, the potential minimum is expressed as

$$\phi_{S,min} = 2\sqrt{A_1 B_1} + \sigma_1. \quad (7)$$

$V_T$  is defined as the value of  $V_{GS}$  for which  $\phi_{S,min} = 2\phi_F$ . This is solved as

$$V_T = \frac{-\psi_b + \sqrt{\psi_b^2 - 4\Omega_a \psi_c}}{2\Omega_a} \quad (8)$$

where  $\Omega_a$ ,  $\psi_b$ , and  $\psi_c$  are summarized in the Appendix. It is worthwhile to note that  $V_{T,2}$  is more important than  $V_{T,1}$  only when the nanogap length is below several tens of nanometers. This fact is verified by both the analytical  $V_{T,2}$  model and the simulation. Equation (8) and the  $V_T$  model in [21] become

TABLE I  
NOMINAL DEVICE DIMENSIONS USED FOR THE VERIFICATION OF THE ANALYTICAL MODEL WITH THE AID OF THE SILVACO SIMULATOR IN THE BIO-TRANSISTOR

Parameter	Symbol	Value
Gate length	$L_g$	1000 nm
Silicon film doping	$N_A$	$10^{17} \text{ cm}^{-3}$
S/D doping	$N_D$	$10^{20} \text{ cm}^{-3}$
Channel thickness	$t_s$	50 nm
Gate oxide thickness	$t_{ox}$	10 nm
Nanogap length	$L_{gap}$	400 nm
Nanogap thickness	$t_{gap}$	15 nm
Buried oxide thickness	$t_b$	300 nm
Gate top layer ( $G_{top}$ ) workfunction	$\phi_{M,top}$	5.1 V (for Au)
Gate bottom layer ( $G_{bot}$ ) workfunction	$\phi_{M,bot}$	4.5 V (for Cr)

identical expressions when  $L_{gap}$  in this work is considered to be half of the gate length, and  $L_2$  in [21] is set to zero, causing the structures of both devices to return to a conventional SOI MOSFET structure [23].

The sensitivity of the biotransistor is characterized by  $\Delta V_T$  before and after immobilization of the biomolecules. Thereby, it is defined as

$$\Delta V_T = V_T(\varepsilon_{gap} = 1) - V_T(\varepsilon_{gap} = K). \quad (9)$$

This closed form of  $\Delta V_T$  is useful for a comprehensive understanding of the biotransistor in terms of device parameter changes.

## V. RESULTS AND DISCUSSION

The device parameters used for the analytical model of the biotransistor are summarized in Table I. The surface potential distribution along the channel was plotted for various values of  $L_{gap}$  in Fig. 2 with the aid of the analytical model. Distortion of the potential profile is clearly observed under the nanogap region, whereas no deformation of the potential profile is observed in a device without a nanogap device ( $L_{gap} = 0$ ).  $V_{DS}$  is biased at 0.05 V, and  $V_{GS}$  is biased at the onset of  $V_{T0}$ , which is the threshold voltage of the initial device without nanogaps. It should be noted that potential distortion becomes more significant as  $L_{gap}$  increases. Therefore, a sufficiently long  $L_{gap}$  is preferred for enhancement of the sensitivity of the biotransistor because  $V_T$  stemming from the potential minimum is a crucial parameter in determining the detection sensitivity.

In Fig. 3, the calculated  $\Delta V_T$  is compared to the simulated result for different values of  $L_{gap}$  by employment of the SILVACO tool. Two different dielectric constants of the biomolecules to fill the nanogaps are used for verification of the model. A dielectric constant of 2 was chosen for biomaterials with a low dielectric constant. A value of 12 was chosen for

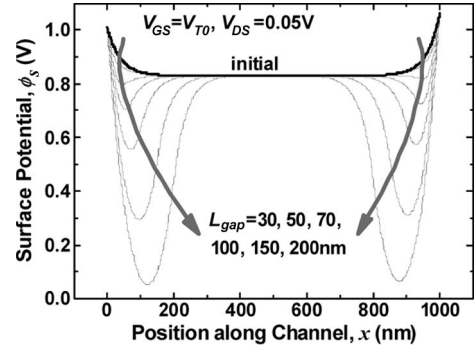


Fig. 2. Surface potential distribution of a conventional MOSFET without a nanogap ( $L_{gap} = 0$ ) and the biotransistor with various nanogap lengths. The distortion of the potential distribution is noticeable under the nanogap region. The increment of  $L_{gap}$  causes more significant potential deformation in the nanogap region.

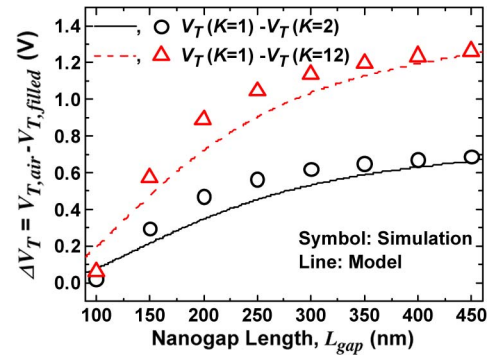


Fig. 3. Dependence of the  $\Delta V_T$  value on the nanogap length  $L_{gap}$ . A longer  $L_{gap}$  results in higher sensitivity.  $\Delta V_T$  starts to become saturated when  $L_{gap}$  exceeds a certain value.

those with a high dielectric. As expected, a larger value of  $\Delta V_T$  was observed with a longer  $L_{gap}$ . In addition, the increment of  $L_{gap}$  resulted in higher sensitivity ( $\Delta V_T$ ), which is very attractive for application as a biosensor. It is important to note that saturation of  $\Delta V_T$  begins when  $L_{gap}$  exceeds a certain value. This gives a clear indication that  $L_{gap}$  does not have to be as large as possible. An  $L_{gap}$  of 400 nm is acceptable to show reasonable sensitivity. Some discrepancy between the modeled and simulated data may arise from ambiguity in the definition of  $V_T$  at the potential minimum. However, this does not hamper understanding of the parametric dependency of the biotransistor.

Fig. 4 reflects the optimal size of the biotransistor. In Fig. 4(a), the transfer characteristics of the biotransistor for a short versus a long gate length are compared. The ratio of  $L_{gap}$  to  $L_g$  is fixed at 0.4 to form a substantial gate electrode without stiction of  $G_{top}$  against  $G_{bot}$ . In the case of a short gate length, there is no significant  $\Delta V_T$ , revealing that it is not appropriate for a biosensor. In contrast, there is a notable value of  $\Delta V_T$  in a device with a long gate length. In the field of biosensors, device size and scaling are not major concerns because the transducer and readout circuitry size is much larger than the size of the biosensor itself. In Fig. 4(b), the  $\Delta V_T$  characteristic is examined as a function of  $L_g$ .  $\Delta V_T$  is insensitive to  $L_g$  as long as  $L_{gap}$  is fixed at a reasonable value. This trend reveals that the biotransistor may not experience process variability.

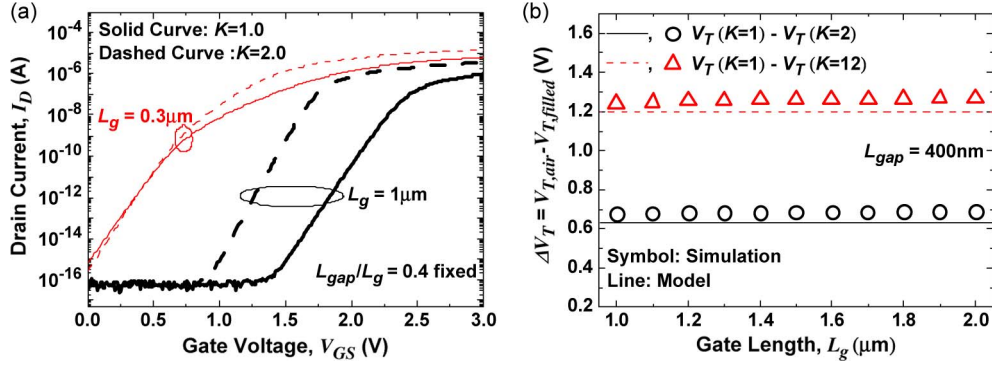


Fig. 4. (a) Transfer characteristics of the biotransistor for different gate lengths with a fixed ratio of  $L_{gap}$  to  $L_g$ . Aggressive scaling of  $L_g$  is not appropriate for the biotransistor. (b)  $\Delta V_T$  versus  $L_g$ . The  $L_g$  parameter does not greatly influence the sensitivity of the biotransistor when  $L_{gap}$  is kept constant.

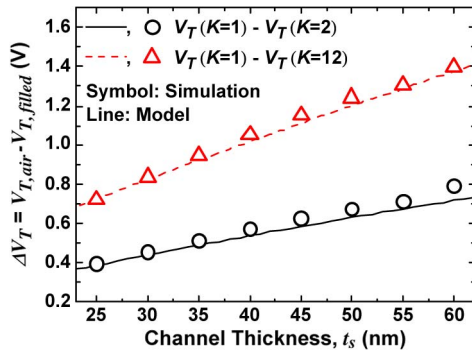


Fig. 5. Dependence of  $\Delta V_T$  on the channel thickness  $t_s$ . A thicker  $t_s$  is preferred for high sensitivity.

Additionally, it supports that the absolute value of  $L_{gap}$  is the key element to determine sensitivity rather than the ratio of  $L_{gap}$  to  $L_g$ . This is because  $V_{T,1}$  at  $R_1$  represents the majority of the total  $V_T$ , which is composed of  $V_{T,1}$ ,  $V_{T,2}$ , and  $V_{T,3}$ , regardless of the length of  $R_2$  on the condition that the value of  $L_{gap}$  is larger than a certain number. In terms of the process,  $L_g$  should be at least slightly longer than twice the distance of  $L_{gap}$  to avoid pattern lift-off during the wet-etching process to carve the sacrificial layer, as nanogaps are formed both at the drain and source sides. For example,  $L_g$  of  $1 \mu\text{m}$  and  $L_{gap}$  of  $400 \text{ nm}$  are feasible for a biotransistor to be used as a biosensor without sacrifice of the mechanical stability in  $G_{top}$ .

The thickness of the channel in SOI devices can be an important factor that affects the characteristics of the device. Fig. 5 shows the tendency in which  $\Delta V_T$  linearly increases as the channel thickness becomes thicker. The modeled data show good agreement with the simulated result. An approximate sensitivity improvement of 70% is expected when the channel thickness doubles. This trend is attributed to the increased depletion charges in the thickened channel. This implies that the entire depletion region in a fully depleted SOI device contributes to the biomolecular detection characteristics.

The thickness of the gate oxide is also a crucial parameter in the control of  $V_T$ . Thermally grown oxide is preferred to ensure stable device performance, as demonstrated in a recent study [16]. The effect of the thickness of the gate oxide was also investigated, as shown in Fig. 6(a). Detection sensitivity ( $\Delta V_T$ ) is independent of the gate oxide thickness, regardless of

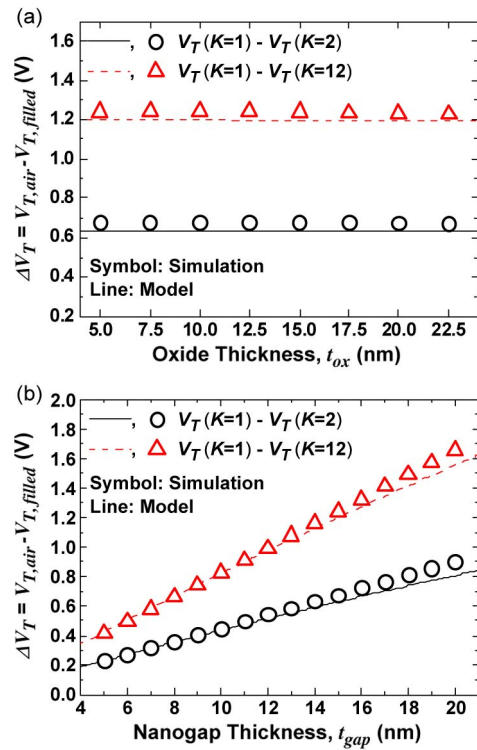


Fig. 6. (a) Dependence of  $\Delta V_T$  on the oxide thickness  $t_{ox}$ . The parameter  $t_{ox}$  does not greatly influence the sensitivity of the biotransistor. (b) Dependence of  $\Delta V_T$  on the nanogap thickness  $t_{gap}$ .

the dielectric constant of the biomolecules. This implies that the gate oxide thickness is a parameter that can be decoupled from other device parameters in maximizing the performance of a MOSFET without specific consideration of the biomolecules. On the other hand, it supports that the sensitivity is entirely governed not by the gate oxide thickness but by the nanogap dimensions. Another confirmation of this fact is shown in Fig. 6(b).  $\Delta V_T$  linearly increases as  $t_{gap}$  becomes thicker. For simplicity, it is assumed that the nanogap is completely filled by biomolecules. As expected, a larger nanogap thickness results in a larger value of  $\Delta V_T$ . However, the nanogap thickness should be adjusted to the size of the targeted biomolecules. It should be comparable or thick enough to accommodate the targeted biomolecules.

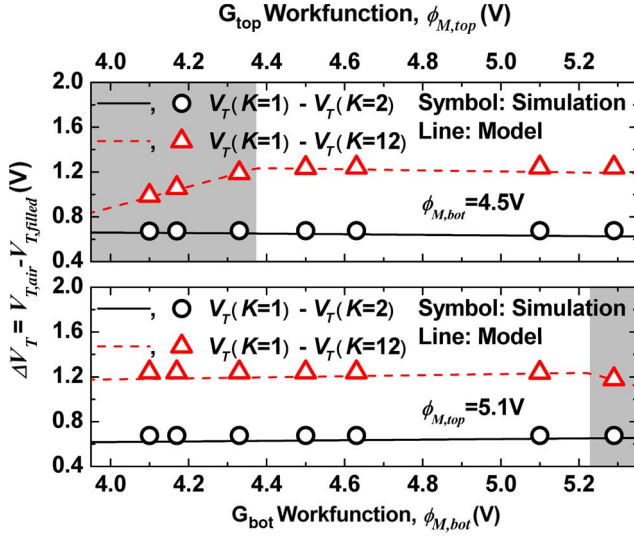


Fig. 7. Dependence of  $\Delta V_T$  on the workfunction in the hybrid gate electrode. Selection of a workfunction of  $G_{top}$  higher than that of  $G_{bot}$  assures a robust  $\Delta V_T$ , which is not affected by the sacrificial layer of  $G_{bot}$ .

Thus far, comprehensive studies of the presented model have been investigated for a nanogap-embedded FET structure with gold as the  $G_{top}$  layer and chromium as the  $G_{bot}$  layer. However, it should be recalled that the primary purpose of  $G_{bot}$  is to serve as a sacrificial layer to form the nanogap, whereas that of  $G_{top}$  is to provide binding sites to accommodate biomolecules with high selectivity to inhibit the biomolecules from being immobilized onto other nondesigned surfaces such as the source, drain, gate oxide, and  $G_{bot}$ . Accordingly, the  $G_{top}$  material whose surface is more likely to bind with target biomolecules is preferred. In terms of biocompatibility, gold is attractive for  $G_{top}$  due to its excellent biostability and chemical stability. Chromium is highly appropriate for  $G_{bot}$  because it can serve as both a sacrificial layer and a glue layer that holds the gold onto the oxide. However, sufficient etching selectivity against the  $G_{top}$  material is a prerequisite for the material for  $G_{bot}$ . Hence, selection of the gate material must be properly optimized.

In terms of device operation, it is desirable that the workfunction of this hybrid gate electrode does not impact the value of  $\Delta V_T$  significantly. Fig. 7 exhibits how  $\Delta V_T$  depends on the material property of the  $G_{top}$  and  $G_{bot}$  layer, i.e., the gate workfunction. In the proposed structure, there are three regions that show different workfunctions:  $\phi_{M,top}$  is the gate workfunction at  $R_1$  and  $R_3$ , whereas  $\phi_{M,bot}$  is the gate workfunction at  $R_2$ . The figure in the upper part of Fig. 7 shows the impact of  $\phi_{M,top}$  on  $\Delta V_T$  when  $\phi_{M,bot}$  is fixed, whereas the lower part of this figure shows the impact of  $\phi_{M,bot}$  on  $\Delta V_T$  when  $\phi_{M,top}$  is fixed. As long as  $\phi_{M,top}$  is larger than  $\phi_{M,bot}$ ,  $\Delta V_T$  is insensitive to the workfunction of the hybrid gate electrode on the biotransistor. Therefore, the selection of gate materials must be done to ensure that  $\phi_{M,top}$  is larger than  $\phi_{M,bot}$ . As gold is known to have a workfunction that is approximately 0.6 V higher than chromium, the proposed hybrid gate structure of gold–chromium in [15] can ensure a stable value of  $\Delta V_T$ .

## VI. CONCLUSION

The analytical surface potential distribution of a biotransistor has been investigated, and an analytical threshold voltage model has been derived from the potential model. The proposed threshold voltage model has comprehensively explained the unique characteristics of the biotransistor and showed good agreement with the simulated data. It has provided how each device parameter affects the sensitivity extrinsically. The proposed analytical model can provide a useful guideline for the optimization of device dimensions to maximize sensitivity of biotransistors.

## APPENDIX

The coefficients  $A_j$  and  $B_j$  in (5) are represented as

$$A_1 = \frac{2V_{DS} + (V_{bi} - \sigma_1)\chi_A + 2(\sigma_1 - \sigma_2)P}{Q} \quad (\text{A-1})$$

$$B_1 = \frac{-2V_{DS} - (V_{bi} - \sigma_1)\chi_B - 2(\sigma_1 - \sigma_2)P}{Q} \quad (\text{A-2})$$

$$A_2 = \frac{1}{2}(\sigma_1 - \sigma_2) \exp(-\lambda_2 L_1) + \frac{1}{2} \left(1 + \frac{\lambda_1}{\lambda_2}\right) \exp((\lambda_1 - \lambda_2)L_1) A_1 + \frac{1}{2} \left(1 - \frac{\lambda_1}{\lambda_2}\right) \exp(-(\lambda_1 + \lambda_2)L_1) B_1 \quad (\text{A-3})$$

$$B_2 = \frac{1}{2}(\sigma_1 - \sigma_2) \exp(\lambda_2 L_1) + \frac{1}{2} \left(1 - \frac{\lambda_1}{\lambda_2}\right) \exp((\lambda_1 + \lambda_2)L_1) A_1 + \frac{1}{2} \left(1 + \frac{\lambda_1}{\lambda_2}\right) \exp(-(\lambda_1 - \lambda_2)L_1) B_1 \quad (\text{A-4})$$

$$A_3 = \frac{1}{2}(\sigma_2 - \sigma_1) \exp(-\lambda_1(L_1 + L_2)) + \frac{1}{2} \left(1 + \frac{\lambda_2}{\lambda_1}\right) \exp((\lambda_2 - \lambda_1)(L_1 + L_2)) A_2 + \frac{1}{2} \left(1 - \frac{\lambda_2}{\lambda_1}\right) \exp(-(\lambda_2 + \lambda_1)(L_1 + L_2)) B_2 \quad (\text{A-5})$$

$$B_3 = \frac{1}{2}(\sigma_2 - \sigma_1) \exp(\lambda_1(L_1 + L_2)) + \frac{1}{2} \left(1 - \frac{\lambda_2}{\lambda_1}\right) \exp((\lambda_2 + \lambda_1)(L_1 + L_2)) A_2 + \frac{1}{2} \left(1 + \frac{\lambda_2}{\lambda_1}\right) \exp(-(\lambda_2 - \lambda_1)(L_1 + L_2)) B_2 \quad (\text{A-6})$$

where

$$\chi_A = 2 - 2 \exp(-2\lambda_1 L_1) \cosh(\lambda_2 L_2) + \left(\frac{\lambda_1}{\lambda_2} + \frac{\lambda_2}{\lambda_1}\right) \exp(-2\lambda_1 L_1) \sinh(\lambda_2 L_2) + \left(\frac{\lambda_1}{\lambda_2} - \frac{\lambda_2}{\lambda_1}\right) \sinh(\lambda_2 L_2) \quad (\text{A-7})$$

$$\begin{aligned} \chi_B &= 2 - 2 \exp(2\lambda_1 L_1) \cosh(\lambda_2 L_2) \\ &\quad - \left( \frac{\lambda_1}{\lambda_2} + \frac{\lambda_2}{\lambda_1} \right) \exp(2\lambda_1 L_1) \sinh(\lambda_2 L_2) \\ &\quad - \left( \frac{\lambda_1}{\lambda_2} - \frac{\lambda_2}{\lambda_1} \right) \sinh(\lambda_2 L_2) \end{aligned} \quad (\text{A-8})$$

$$\begin{aligned} P &= \cosh(\lambda_1 L_1) (1 - \cosh(\lambda_2 L_2)) \\ &\quad - (\lambda_2 / \lambda_1) \sinh(\lambda_1 L_1) \sinh(\lambda_2 L_2) \end{aligned} \quad (\text{A-9})$$

$$\begin{aligned} Q &= 4 \sinh(2\lambda_1 L_1) \cosh(\lambda_2 L_2) \\ &\quad + 2 \left( \frac{\lambda_1}{\lambda_2} + \frac{\lambda_2}{\lambda_1} \right) \cosh(2\lambda_1 L_1) \sinh(\lambda_2 L_2) \\ &\quad + 2 \left( \frac{\lambda_1}{\lambda_2} - \frac{\lambda_2}{\lambda_1} \right) \sinh(\lambda_2 L_2). \end{aligned} \quad (\text{A-10})$$

The complicated expressions of the coefficients  $\Omega_a$ ,  $\psi_b$ , and  $\psi_c$  in (8) are briefly represented as

$$\Omega_a = 4\tau_A \tau_B - S_1^2 Q^2 \quad (\text{A-11})$$

$$\psi_b = 4(\tau_A V_{DS,B} + \tau_B V_{DS,A}) - 2S_1 Q^2 (u_1 - 2\phi_F) \quad (\text{A-12})$$

$$\psi_c = 4V_{DS,A} V_{DS,B} - Q^2 (u_1 - 2\phi_F)^2 \quad (\text{A-13})$$

where

$$S_1 = \frac{C_{\text{eff}}/C_S + C_{\text{eff}}/C_B}{1 + C_{\text{eff}}/C_S + C_{\text{eff}}/C_B} \quad (\text{A-14})$$

$$S_2 = \frac{C_{\text{ox}}/C_S + C_{\text{ox}}/C_B}{1 + C_{\text{ox}}/C_S + C_{\text{ox}}/C_B} \quad (\text{A-15})$$

$$\begin{aligned} u_1 &= (V_{\text{SUB}} - V_{\text{FB},b}) \left( \frac{1}{1 + C_{\text{eff}}/C_S + C_{\text{eff}}/C_B} \right) \\ &\quad - \frac{qN_A t_s^2 (1 + 2C_S/C_B)}{2\varepsilon_{\text{Si}} (1 + C_{\text{eff}}/C_S + C_{\text{eff}}/C_B)} - S_1 V_{\text{FB},1} \end{aligned} \quad (\text{A-16})$$

$$\begin{aligned} u_2 &= (V_{\text{SUB}} - V_{\text{FB},b}) \left( \frac{1}{1 + C_{\text{ox}}/C_S + C_{\text{ox}}/C_B} \right) \\ &\quad - \frac{qN_A t_s^2 (1 + 2C_S/C_B)}{2\varepsilon_{\text{Si}} (1 + C_{\text{ox}}/C_S + C_{\text{ox}}/C_B)} - S_2 V_{\text{FB},2} \end{aligned} \quad (\text{A-17})$$

$$\tau_A = 2(S_1 - S_2)P - S_1 \chi_A \quad (\text{A-18})$$

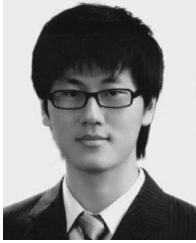
$$V_{DS,A} = 2V_{DS} + (V_{\text{bi}} - u_1) \chi_A + 2(u_1 - u_2)P \quad (\text{A-19})$$

$$\tau_B = -2(S_1 - S_2)P + S_1 \chi_B \quad (\text{A-20})$$

$$\begin{aligned} V_{DS,B} &= -2V_{DS} - (V_{\text{bi}} - u_1) \chi_B - 2(u_1 - u_2)P. \end{aligned} \quad (\text{A-21})$$

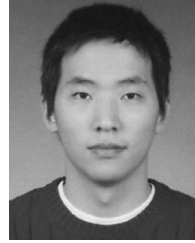
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